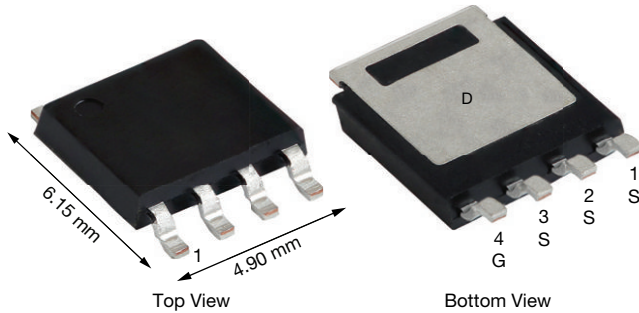




Automotive N-Channel 150 V (D-S) 175 °C MOSFET

PowerPAK® SO-8L



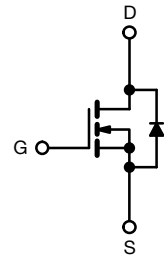
FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE GRADE



RoHS COMPLIANT HALOGEN FREE



N-Channel MOSFET

PRODUCT SUMMARY	
V _{DS} (V)	150
R _{DS(on)} (Ω) at V _{GS} = 10 V	0.0098
I _D (A) ^e	98
Configuration	Single

ORDERING INFORMATION	
Package	PowerPAK® SO-8L
Lead (Pb)-free and halogen-free	SQJ590EP (for detailed order number please see www.vishay.com/doc?79771)

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V _{DS}	150	V
Gate-Source Voltage		V _{GS}	± 20	
Continuous Drain Current ^e	T _C = 25 °C ^a	I _D	98	A
	T _C = 125 °C		56	
Continuous Source Current (Diode conduction) ^e		I _S	98	
Pulsed Drain Current ^{b, e}		I _{DM}	182	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	28	
Single Pulse Avalanche Energy		E _{AS}	39	
Maximum Power Dissipation ^{b, e}	T _C = 25 °C	P _D	245	W
	T _C = 125 °C		81	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C
Soldering Recommendations (Peak temperature)			260	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB mount ^c	R _{thJA}	44	°C/W
Junction-to-Case (Drain) ^d		R _{thJC}	0.61	

Notes

- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %
- When mounted on 1" square PCB (FR4 material)
- See solder profile (www.vishay.com/doc?73257).
- As per on JESD51-14
- Values based on R_{thJC} and T_C of 25 °C. Actual values achievable will be dependent on the thermal characteristics of the complete system.



SPECIFICATIONS ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}$, $I_D = 250\text{ }\mu\text{A}$		150	-	-	V
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$		2.2	3.0	3.5	
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20\text{ V}$		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0\text{ V}$	$V_{DS} = 150\text{ V}$	-	-	10	μA
		$V_{GS} = 0\text{ V}$	$V_{DS} = 150\text{ V}$, $T_J = 125\text{ }^\circ\text{C}$	-	-	100	
		$V_{GS} = 0\text{ V}$	$V_{DS} = 150\text{ V}$, $T_J = 175\text{ }^\circ\text{C}$	-	-	500	
On-State Drain Current ^a	$I_{D(on)}$	$V_{GS} = 10\text{ V}$	$V_{DS} \geq 5\text{ V}$	10	-	-	A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 10\text{ A}$	-	0.0082	0.0098	Ω
		$V_{GS} = 10\text{ V}$	$I_D = 10\text{ A}$, $T_J = 125\text{ }^\circ\text{C}$	-	-	0.020	
		$V_{GS} = 10\text{ V}$	$I_D = 10\text{ A}$, $T_J = 175\text{ }^\circ\text{C}$	-	-	0.028	
Forward Transconductance ^b	g_{fs}	$V_{DS} = 15\text{ V}$, $I_D = 20\text{ A}$		-	70	-	S
Dynamic ^b							
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$	-	3301	4622	μF
Output Capacitance	C_{oss}			-	1316	1843	
Reverse Transfer Capacitance	C_{rss}			-	25	35	
Total Gate Charge ^c	Q_g	$V_{GS} = 10\text{ V}$	$V_{DS} = 75\text{ V}$, $I_D = 25\text{ A}$	-	34	52	nC
Gate-Source Charge ^c	Q_{gs}			-	15	-	
Gate-Drain Charge ^c	Q_{gd}			-	2	-	
Gate Resistance	R_g	f = 1 MHz		0.6	1.5	2.4	Ω
Turn-On Delay Time ^c	$t_{d(on)}$	$V_{DD} = 75\text{ V}$, $R_L = 3\text{ }\Omega$ $I_D \cong 25\text{ A}$, $V_{GEN} = 10\text{ V}$, $R_g = 1\text{ }\Omega$		-	14	21	ns
Rise Time ^c	t_r			-	19	29	
Turn-Off Delay Time ^c	$t_{d(off)}$			-	21	32	
Fall Time ^c	t_f			-	16	24	
Source-Drain Diode Ratings and Characteristics ^b							
Pulsed Current ^a	I_{SM}			-	-	182	A
Forward Voltage	V_{SD}	$I_F = 10\text{ A}$, $V_{GS} = 0\text{ V}$		-	0.88	1.2	V
Body diode reverse recovery time	t_{rr}	$I_F = 10\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$		-	74	148	ns
Body diode reverse recovery charge	Q_{rr}			-	240	480	nC
Reverse recovery fall time	t_a			-	57	-	ns
Reverse recovery rise time	t_b			-	109	-	
Body diode peak reverse recovery current	$I_{RM(REC)}$					-	-7.0

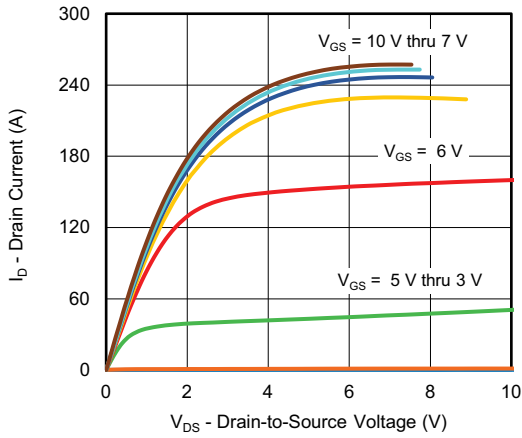
Notes

- Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
- Guaranteed by design, not subject to production testing
- Independent of operating temperature

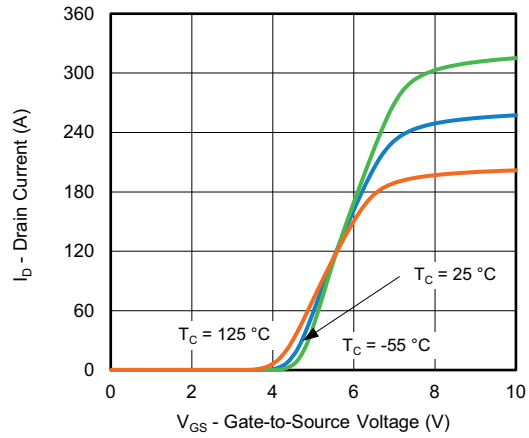
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



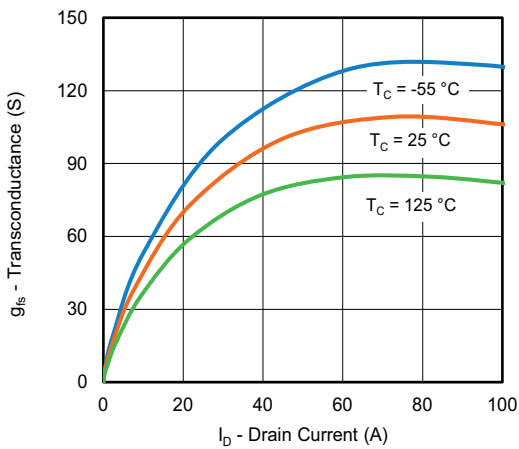
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



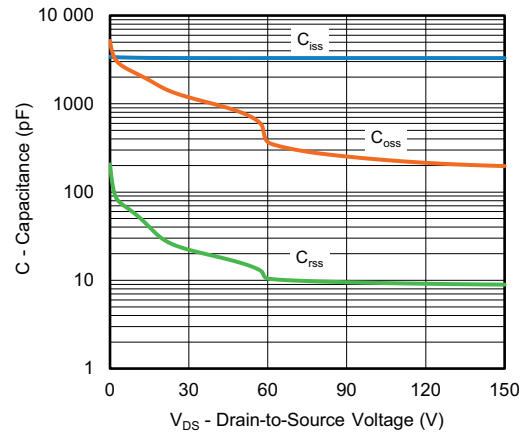
Output Characteristics



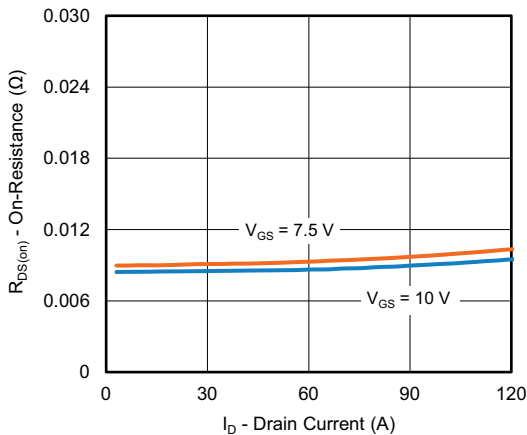
Transfer Characteristics



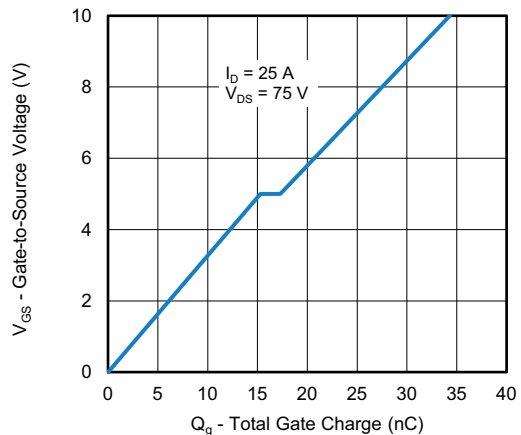
Transconductance



Capacitance

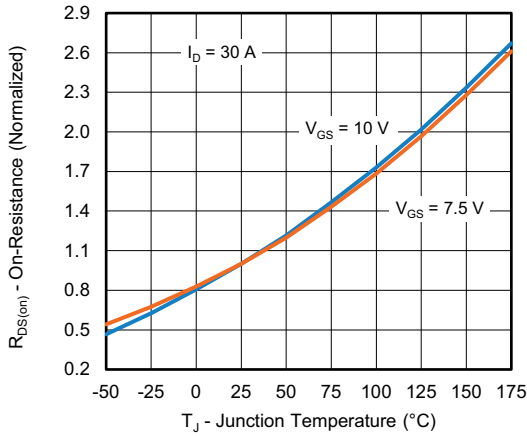


On-Resistance vs. Drain Current

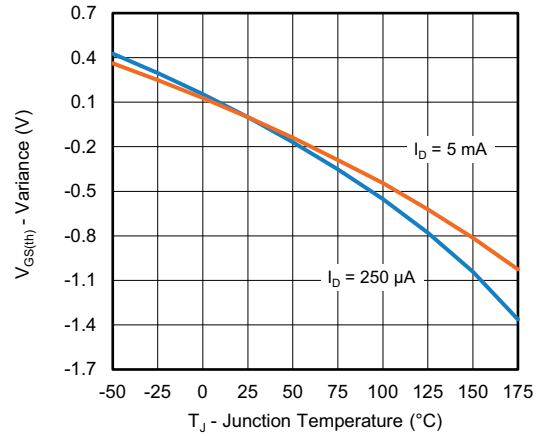


Gate Charge

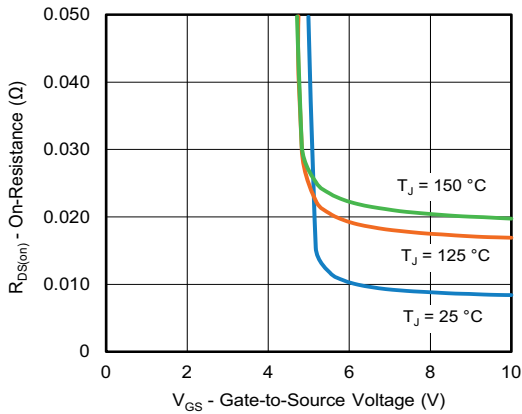
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



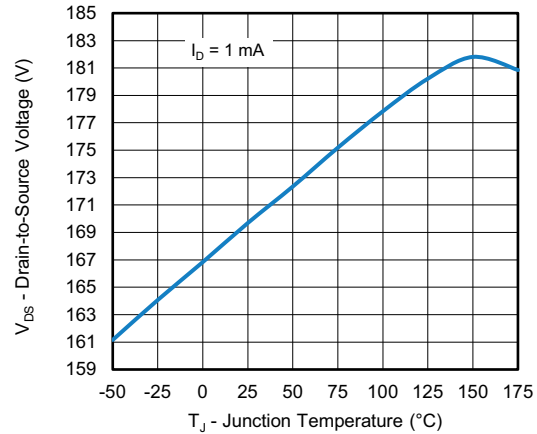
On-Resistance vs. Junction Temperature



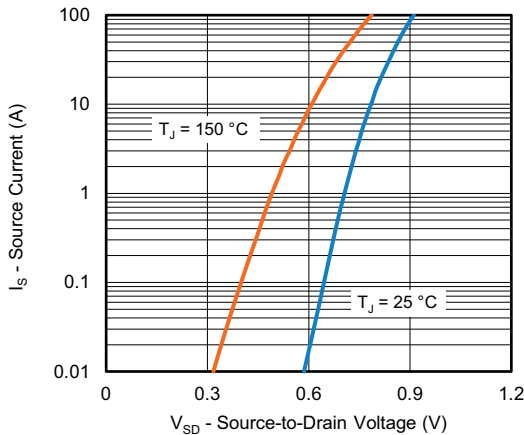
Threshold Voltage



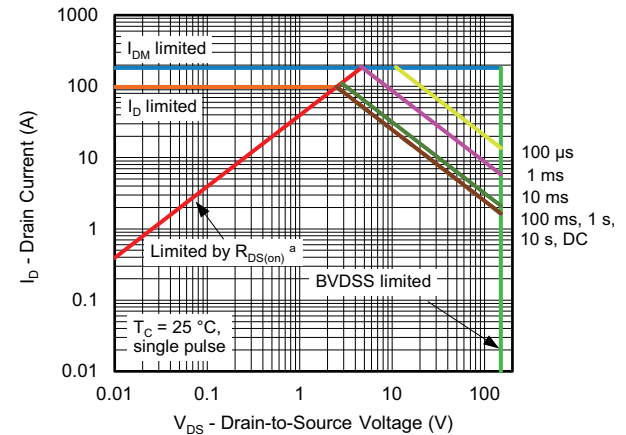
On-Resistance vs. Gate-to-Source Voltage



Drain Source Breakdown vs. Junction Temperature



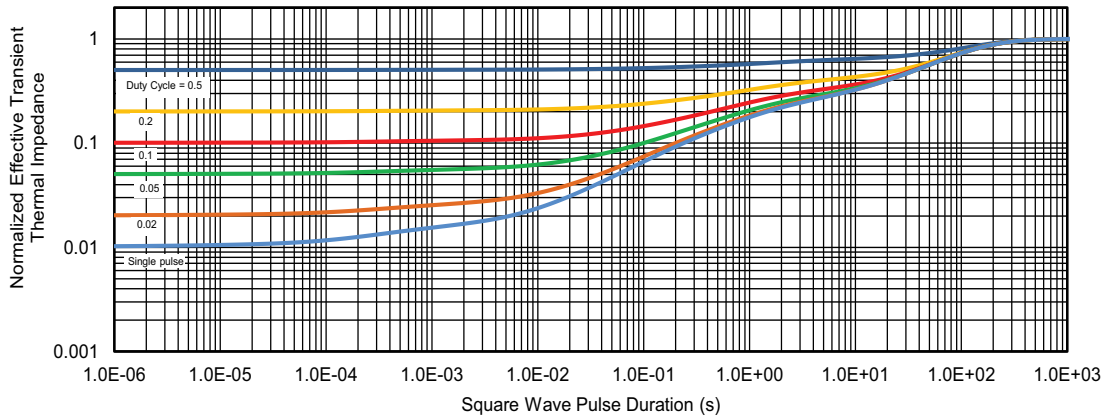
Source Drain Diode Forward Voltage



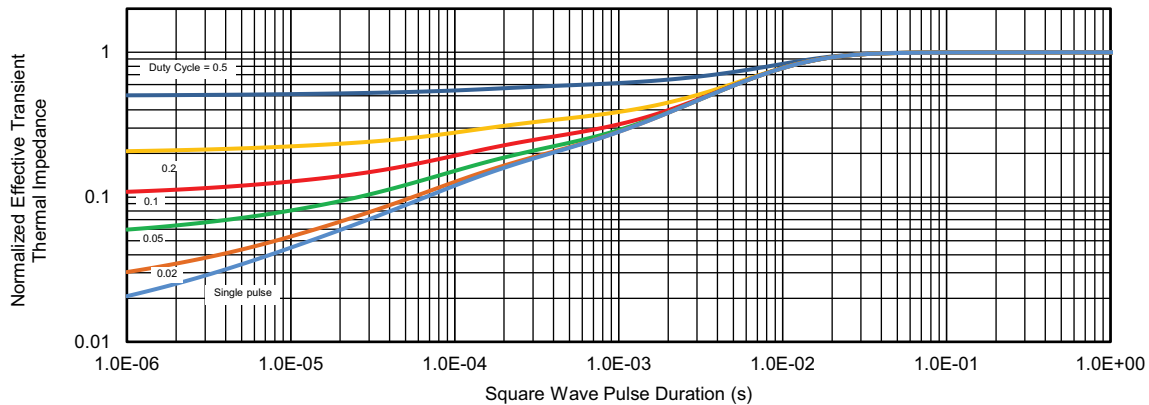
Safe Operating Area



THERMAL RATINGS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)
 are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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